

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT6365314

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HANSEL DESMOND DSILVA	10/16/2020
SASIKALA J	10/17/2020
ABHISHEK JAIN	10/20/2020
AMIT KUMAR	10/13/2020
RECEIVING PARTY DATA	
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Street Address:	PO BOX 2938
City:	MINNEAPOLIS
State/Country:	MINNESOTA
Postal Code:	55402
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17078471
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Address Line 4:	MINNEAPOLIS, MINNESOTA 55402
ATTORNEY DOCKET NUMBER:	2695.043US1
NAME OF SUBMITTER:	ROBYN MILLER
SIGNATURE:	/ROBYN MILLER/
DATE SIGNED:	10/23/2020
Total Attachments: 6	
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ASSIGNMENT

WHEREAS, Hansel Desmond Dsilva, Sasikala J, Abhishek Jain and Amit Kumar (hereinafter the "Undersigned") have made one or more inventions and other subject matter (hereinafter collectively referred to as the "Invention"); as described in the patent application filed on 10/23/2020, assigned US application serial number 17/078,471, and titled Capacitive Compensation for Vertical Interconnect Accesses.

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency, and adequacy of which are hereby acknowledged by the Undersigned, the Undersigned do hereby irrevocably and unconditionally:

CONVEY, ASSIGN, AND TRANSFER to Achronix Semiconductor Corporation (the "Assignee"), a corporation of the State of Delaware, having a place of business at 2903 Bunker Hill Lane, Suite 200, Santa Clara, CA 95054, the Undersigned's entire right, title, and interest for the United States and all foreign countries and jurisdictions in and to:

the Invention which is disclosed in the above-identified application or applications;

such application or applications, and all divisional, continuing (including continuation-in-part), substitute, renewal, reissue, and all other applications for a patent or patents which have been or shall be filed in the United States (including all provisional and non-provisional applications), and in all foreign countries and jurisdictions based in whole or in part on any of such Invention (including any application for a utility model or an innovation patent application);

all original and reissued patents which have been or shall be issued in the United States and all foreign countries and jurisdictions based in whole or in part on any of such Invention;

including the right to claim priority to the above-identified patent application or applications in relation to subject matter based in whole or in part on the above-identified patent application or applications and any of the foregoing including the right to file foreign applications under the provisions of any convention or treaty;

and including the right to all causes of action, remedies, and other enforcement rights related to the above-identified application or applications, including without limitation the right to sue for past, present, or future infringement, misappropriation, or violation of any and all rights related to the above-identified patent application or applications and any of the foregoing, including the right to obtain and collect damages for past, present, or future infringement;

AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on such Invention to the Assignee;

AUTHORIZE AND REQUEST that any attorney associated with U.S. Patent and Trademark Office (USPTO) Customer No. 21186 may (directly or through his/her designee) delete, insert, or alter any information related to the above-identified patent application or applications or any of the foregoing, after execution of this Assignment;

Assignment

Assignors: Hansel Desmond Dsilva et al.

Title: Capacitive Compensation for Vertical Interconnect Accesses

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Docket No: 2695.043US1

WARRANT AND COVENANT that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or shall be made to others by the Undersigned, and that the full right to convey the same as herein expressed is possessed by the Undersigned;

COVENANT, that when requested and without compensation, but at the expense of the Assignee, in order to carry out in good faith the intent and purpose of this Assignment, the Undersigned shall (1) execute all provisional, non-provisional, divisional, continuing (including continuation-in-part), substitute, renewal, reissue, and all other patent applications for the Invention; (2) execute all rightful oaths, declarations, assignments, powers of attorney and other papers for the Invention; (3) communicate to the Assignee all facts known to the Undersigned relating to the Invention and the history thereof; (4) cooperate with the Assignee in any interference, reexamination, reissue, opposition, dispute, or litigation involving any of the applications or patents for the Invention; and (5) take such further actions as the Assignee shall reasonably consider necessary or desirable for vesting title to such Invention in the Assignee, or for securing, maintaining and enforcing proper patent protection for the Invention;

COVENANT, that should any provision of this agreement be held unenforceable by an authority of competent jurisdiction, such a ruling shall not affect the validity and enforceability of the remaining provisions.

THIS AGREEMENT IS TO BE BINDING on the heirs, assigns, representatives, and successors of the Undersigned, and is to extend to the benefit of the successors, assigns, and nominees of the Assignee.

AGREED as of the date of my signature below:

Assignment

Docket No: 2695.043US1

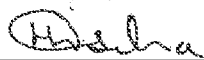
Assignors: Hansel Desmond Dsilva et al.

Title: Capacitive Compensation for Vertical Interconnect Accesses

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Assignor:

(Signature):



Name: Hansel Desmond Dsilva

City/State or Country: Mumbai, Maharashtra, India

Date:

16th October 2020

Assignment:

Docket No. 2695/043US1

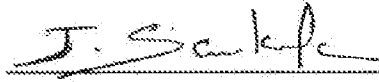
Assignors: Hansel Desmond Dsilva et al.

Title: Capacitive Compensation for Vertical Interconnect Accesses

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Assignor:

(Signature):



Name: Sasikala J.

City/State or Country: Chennai, Tamilnadu, India

Date:

17-10-2020

Assignment

Assignors: Hansel Desmond Dailys et al.

Title: Capacitive Compensation for Vertical Interconnect Assemblies

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Docket No. 3695 043US1

Assignor:

(Signature):

Abhishek Jain

Name: Abhishek Jain

City/State or Country: New Delhi / India

Date:

20/10/2020

PATENT

REEL: 054149 FRAME: 0128

Assignment

Docket No: 2695 043US1

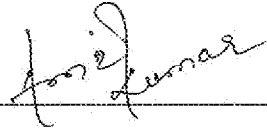
Assignors: Hansel Desmond Dsilva et al.

Title: Capacitive Compensation for Vertical Interconnect Accesses

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Assignor:

(Signature):



Name: Amit Kumar

City/State or Country: Noida, India

Date:

13-10-2020